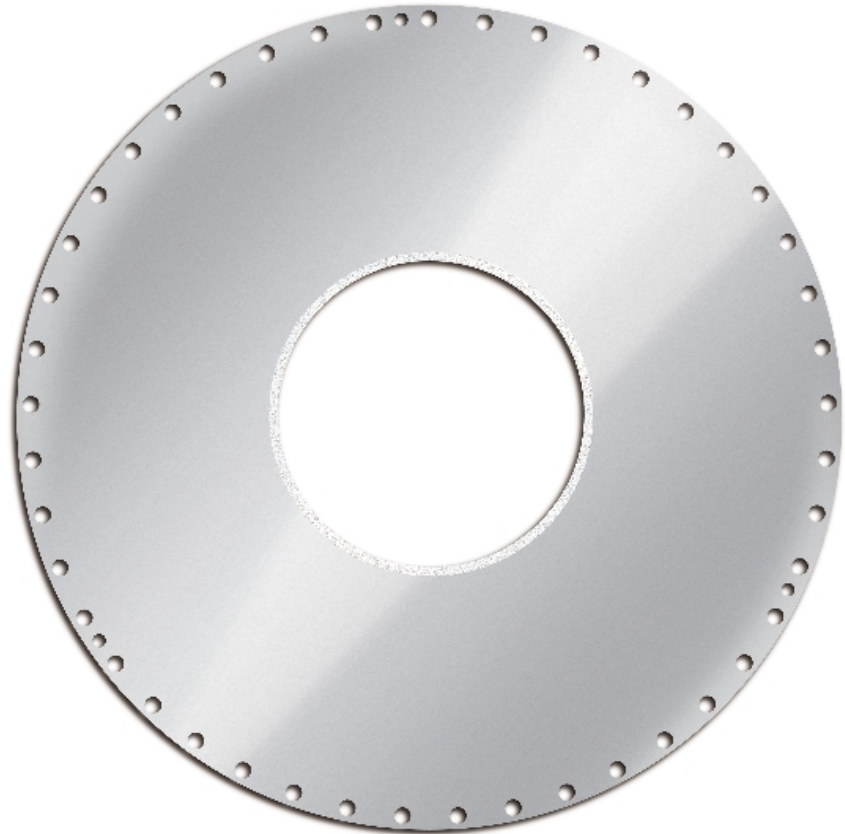




SMI - Diamond I.D. Slicing Blades



- ❖ ***SMI patented multilayered diamond I.D. slicing blades are specifically designed & manufactured to maximize wafer yields in all types of semiconductor materials.***
- ❖ ***The diamond rim is designed to "minimize" ingot waste, and the patented multilayered rim depth (.015 min.) "maximizes" blade life.***
- ❖ ***Only the finest 100% natural virgin DeBeers diamonds are used to minimize wafer surface and subsurface damage.***
- ❖ ***The I.D. Blade and its high speed, creep resistant core material is specifically manufactured to allow higher tensioning, minimizing blade bow, saw marks, and exit chipping.***

